



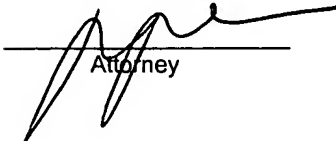
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27,922

Reg. No.

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of:

Applicant : Lawrence E. Gebhart et al.
Appln. No. : 10/804,841
Filed : March 19, 2004
Title : ELECTROPLATING CELL WITH HYDRODYNAMICS
FACILITATING MORE UNIFORM DEPOSITION ACROSS A
WORKPIECE DURING PLATING
Docket No. : 461987-024
Art Unit : 1742

Commissioner for Patents
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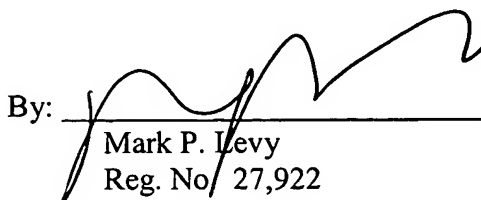
INFORMATION DISCLOSURE STATEMENT

Pursuant to 37 C.F.R. §1.56, the Examiner's attention is directed to the references listed on the attached Information Disclosure Citation. Copies of all non-patent literature references are provided herewith.

It is to be understood that the present submission of art is in no way intended to be a waiver of any arguments or defenses available to the applicant under the rules of the U.S. Patent and Trademark Office and the statutes of the United States.

No fee is required. The Commissioner is authorized to charge any additional fees required by this paper or to credit any overpayment to Deposit Account No. 20-0809.

Respectfully submitted:

By: 
Mark P. Levy
Reg. No. 27,922

Application No.: 10/804,841
Docket No.: 461987-024
Information Disclosure Statement

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INFORMATION DISCLOSURE CITATION

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| Docket: 461987-024 | Appln. No.: 10/804,841 |
| Applicant: Lawrence E. Gebhart et al. | |
| Filed: 03/19/2004 | Group: 1742 |

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